

# EDCON-COMPONENTS

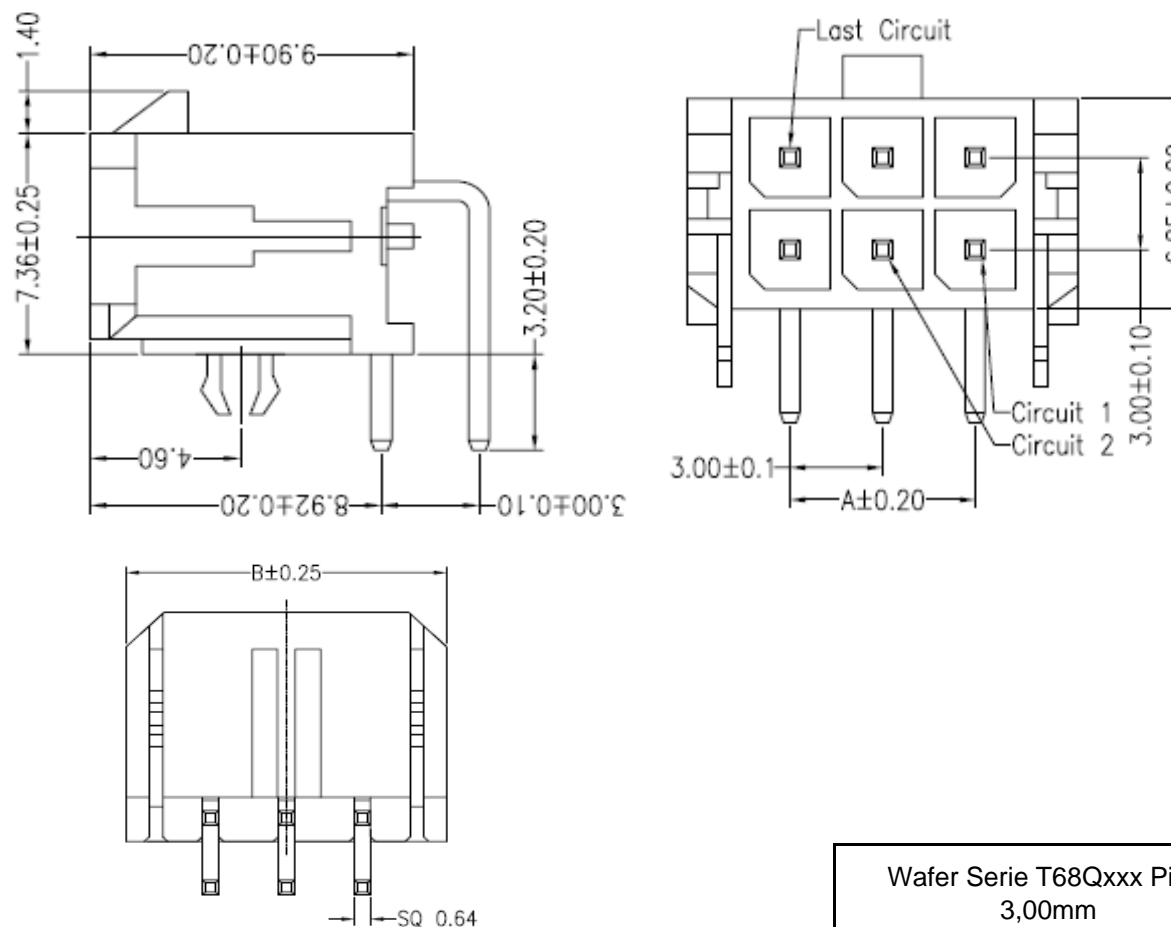


## Specifications

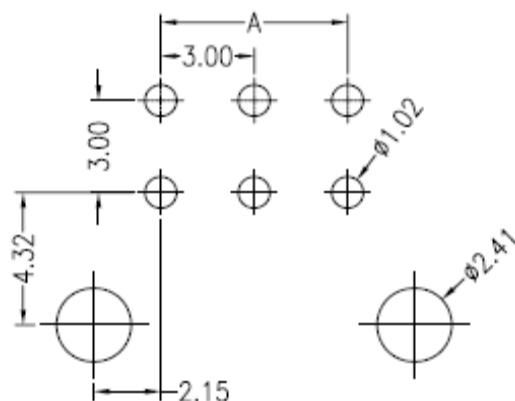
Voltage Rating: 250VAC/DC  
 Current Rating: 5,0A  
 Operating Temperature: -25°C ~ +85°C  
 Contact Resistance: 10m Ohm max.  
 Withstanding Voltage: 1500VAC/Minute  
 Insulation Resistance: 1000M Ohm min.

Contact Material: Brass  
 Contact Plating: AU or Sn over Ni.  
 Insulator Material: High Temperature Plastic  
 UL94V-0

## Drawing ( dimensions all into mm)



## Terminal Assembly Drawing



Wafer Serie T68Qxxx Pitch  
3,00mm

Part No.: **T68Q023**

Customer:

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	02.04.2009
APPD:	Schumi			FINISH	Jamy			Sheet No.	1 from 4

# EDCON-COMPONENTS



## Dimension Informations about Wafer

Pos.	Dimension (mm)					
	A	B	C	D	E	F
2		6,65				
4	3,00	9,65				
6	6,00	12,65				
8	9,00	15,65				
10	12,00	18,65				
12	15,00	21,65				
14	18,00	24,65				
16	21,00	27,65				
18	24,00	30,65				
20	27,00	33,65				
22	30,00	36,65				
24	33,00	39,65				

Pos.	Dimension (mm)					
	A	B	C	D	E	F

Wafer Serie T68Qxxx Pitch 3,00mm

Part No.: **T68Q023**

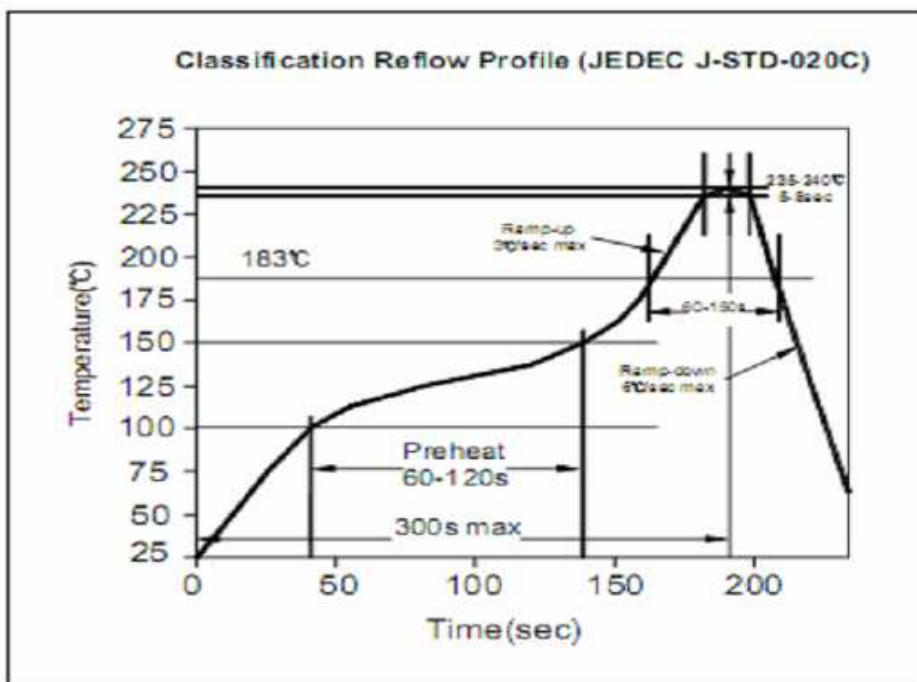
Customer:

DRW: Jason	CHKD: Wilson	MATL: Wilson	TOLERANCE: Mason	DATE: 02.04.2009
APPD: Schumi		FINISH: Jamy	Sheet No.:	2 from 4

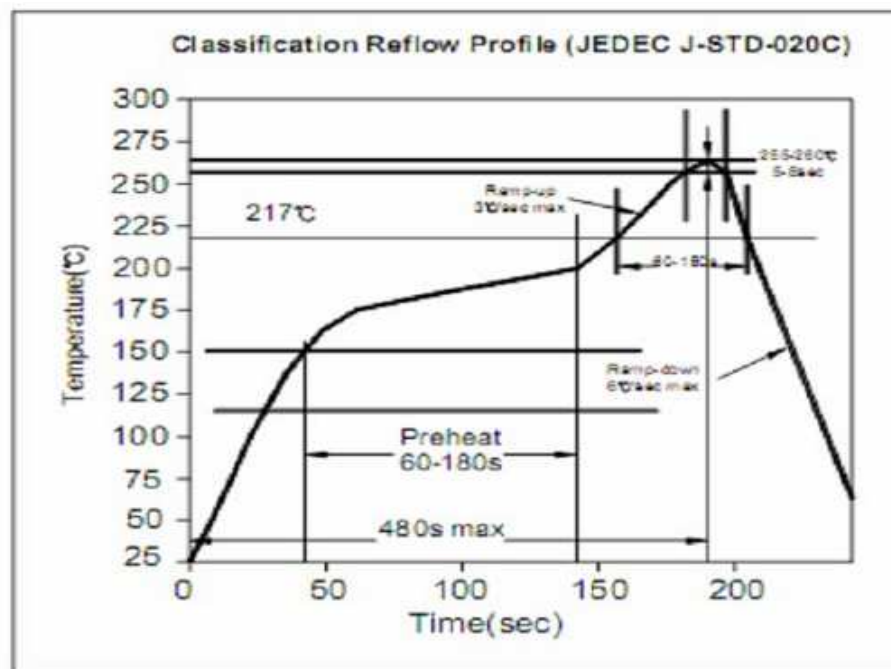


Soldering Profile

Lead Solder



Lead Free Solder



Wafer Serie T68Qxxx Pitch 3,00mm
Part No.: <b>T68Q023</b>
Customer:

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	02.04.2009
APPD:	Schumi			FINISH	Jamy		Sheet No.	3 from 4	

# EDCON-COMPONENTS



## Ordering Informations

Serie	Number of	Contact	Packing						
<b>T68Q023</b>	<b>02</b>	<b>T</b>	<b>BU</b>						

<b>xx = Pos.</b>	<b>T= Tin Plated (Standard)</b>	<b>BU= Bulk (Standard)</b>							
		<b>TY= Tray Packing</b>							
	<b>G= Gold Flash Plated</b>	<b>TU= Tube Packing</b>							

Wafer Serie T68Qxxx Pitch 3,00mm
Part No.: <b>T68Q023</b>
Customer:

DRW:	Jason	CHKD	Wilson	MATL:	Wilson	TOLERANCE	Mason	DATE	02.04.2009
APPD:	Schumi			FINISH	Jamy		Sheet No.	4 from 4	